

■ Features

- Minature size,suitable for SMT.
- Using terminal electrode structure to restrain the parasitic component effect quite caused by lead.
- Excellent in solderability and heat resistance.
- Best frequency special property and intense ability to resist interference.
- Operating temperature:-40℃ ~ +85℃.

■ Applications

- Protable communication equipment and PDA,high speed electronic device.
- Used for radiation high speed noise suppression.

■ Product Identification



- (1) : Type
- (2) : Dimensions
- (3) : Inductance value
- (4) : Inductance Tolerance: M=±20%,K=±10%,J=±5%

■ Shapes and Dimensions (Unit: mm)



TYPE	A Max.	B Max.	C Max.	D Typ.	E Typ.	F Typ.
YWIF2012	2.40	1.52	1.73	0.76	1.02	1.78

■ YWIF2012 Series

Part Number	L (uH)	Freq. (MHz)	Q Min.	SRF Min. (MHz)	Rdc Max. (Ω)	Isat Max. (mA)
YWIF2012-R12K	0.12±10%	7.9	19	340	0.27	750
YWIF2012-R15K	0.15±10%	7.9	19	480	0.30	720
YWIF2012-R18K	0.18±10%	7.9	19	480	0.40	720
YWIF2012-R22K	0.22±10%	7.9	19	480	0.40	720
YWIF2012-R39K	0.39±10%	25	19	500	0.31	720
YWIF2012-R47K	0.47±10%	7.9	19	500	0.31	720
YWIF2012-R56K	0.56±10%	7.9	12	400	0.46	400
YWIF2012-R68K	0.68±10%	7.9	19	400	0.46	590
YWIF2012-R81K	0.81±10%	7.9	12	360	1.00	520
YWIF2012-1R0K	1.0±10%	7.9	12	360	1.00	430
YWIF2012-1R2K	1.2±10%	7.9	12	350	1.15	410
YWIF2012-1R5K	1.5±10%	7.9	12	300	1.20	400
YWIF2012-1R8K	1.8±10%	7.9	12	300	1.35	380
YWIF2012-2R2K	2.2±10%	7.9	12	170	1.50	350
YWIF2012-2R7K	2.7±10%	7.9	12	100	1.70	320
YWIF2012-3R3K	3.3±10%	7.9	12	90	1.80	300
YWIF2012-3R9K	3.9±10%	7.9	12	90	1.95	280
YWIF2012-4R7K	4.7±10%	7.9	12	85	2.05	250
YWIF2012-5R6K	5.6±10%	7.9	12	70	2.30	240
YWIF2012-6R8K	6.8±10%	7.9	12	55	2.60	220
YWIF2012-8R2K	8.2±10%	7.9	12	50	3.00	180
YWIF2012-100K	10±10%	2.5	10	30	2.55	150
YWIF2012-120K	12±10%	2.5	10	16	3.50	100
YWIF2012-150K	15±10%	2.5	10	16	4.20	100

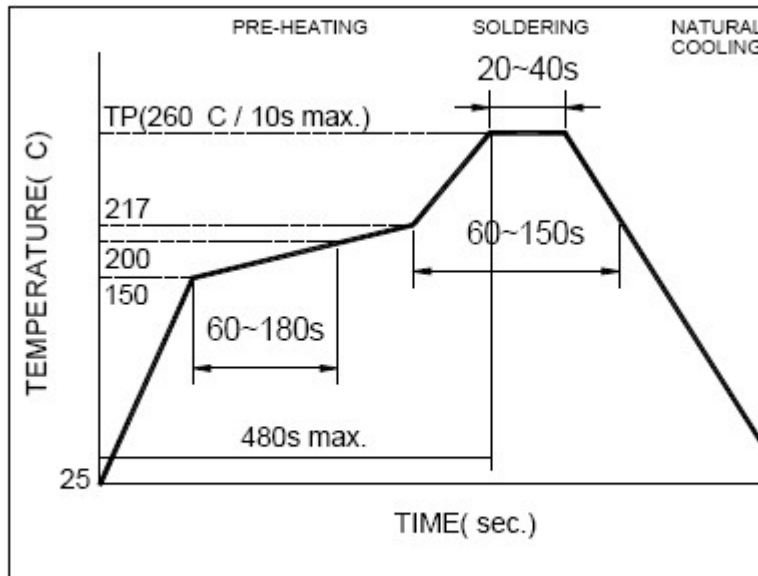
■ YWIF2012 Series

Part Number	L (uH)	Freq. (MHz)	Q Min.	SRF Min. (MHz)	Rdc Max. (Ω)	Isat Max. (mA)
YWIF2012-180K	18±10%	2.5	10	15	4.50	95
YWIF2012-220K	22±10%	2.5	10	14	6.00	80
YWIF2012-270K	27±10%	2.5	10	17	10.70	60
YWIF2012-330K	33±10%	2.5	10	17	10.70	60
YWIF2012-470K	47±10%	2.5	10	14	13.80	55
YWIF2012-680K	68±10%	2.5	8	11	17.50	40
YWIF2012-101K	100±10%	1	8	5	25.00	30
YWIF2012-111K	110±10%	1	8	5	26.00	20

- ※ Rating DC current:temperature rise(ΔT) is 40 °C approximately at Irms.
- ※ Saturation DC current:Inductance drop approximately 30% of L0 at Isat.
- ※ Storage temp.: -10°C ~ + 40°C R.H.:65% Max.
- ※ Moisture sensitivity level(MSL)2(1 year floor life at<30°C/65% relative humidity).

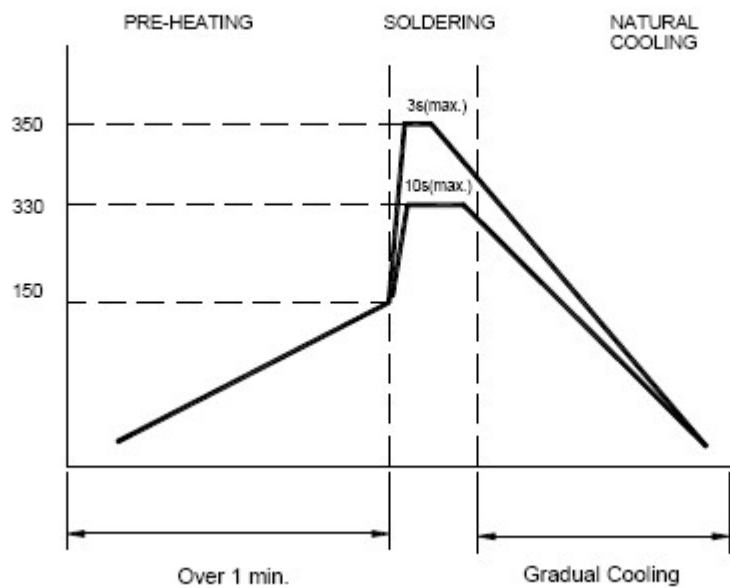
■ Soldering Conditions

**Figure 1.
Re-flow
Soldering
(Lead Free)**



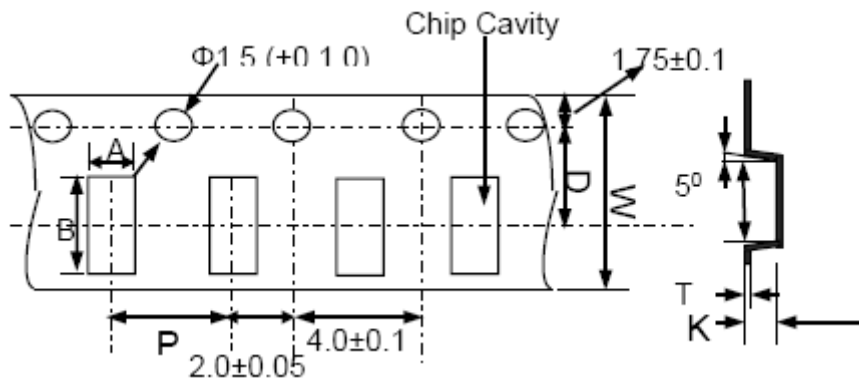
- Note:
- Preheat circuit and products to 150°C
 - 260°C tip temperature (max)
 - Reflow times: no more than 2 times
 - Solder paste thickness: the best 0.08mm is ,but max is 0.1mm

**Figure 2.
Hand
Soldering**



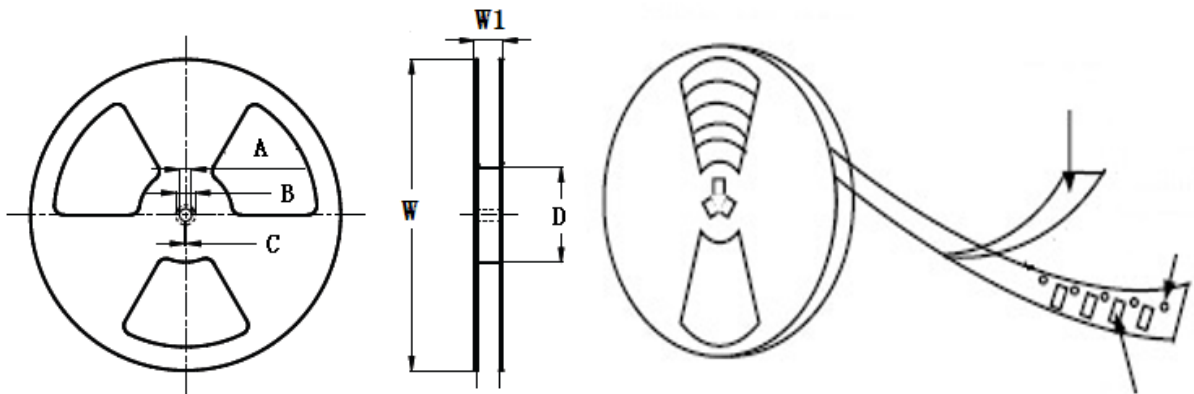
- Note:
- Use a 20 watt soldering iron with tip diameter of 1.0mm
 - Limit soldering time to 3 sec.

■ Taping Dimensions(Unit:mm)



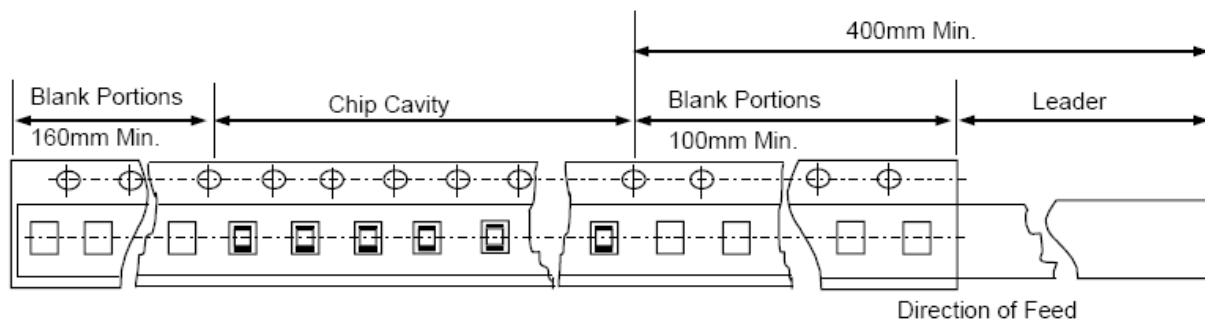
TYPE	W	A	B	D	P	K Max	T Max	MPQ
YWIF2012	8.00	1.50	2.30	3.50	4.00	1.10	0.30	2000

■ Reel Dimensions(Unit:mm)



TYPE	W	W1	A	B	C	D
YWIF2012	178±2.0	8.40±1.50	4.3±0.20	5.0±0.10	3.0±0.10	58±2.0

Leader and Blank portion



1. Missing chips number within 0.1% of the number per reel or 1pcs, whichever is greater, and are not continuous.
2. The top tape and bottom tape shall not protrude beyond the edges of the tape and shall not cover sprocket hole.
3. Cumulative tolerance of sprocket holes, 10 pitches: $\pm 0.3\text{mm}$.
4. Peeling off force: 10gf to 100gf in the direction show below for 8mm carrier tapes and 10gf to 130gf for 12mm to 56mm wide carrier tapes.

